



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-08-03
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD7N60M2	TODP*MQ60B8F	A	Z8GA	2016-08-03
Amount		UoM	Unit type	ST ECOPACK Grade
355.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
SIP	6.5,6.1,2.3	3	gull wing
Comment	Package: TO 252 DPAK		

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TODP*MQ6088F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.425	mg	supplier	die	Silicon (Si)	7440-21-3		3.286	mg	959416	9256
				supplier	metallization	Aluminium (Al)	7429-90-5		0.066	mg	19270	186
				supplier	Passivation	Silicon Nitride	12033-89-5		0.016	mg	4672	45
				supplier	Passivation	Silicon Oxide	7631-86-9		0.024	mg	7007	68
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	584	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.023	mg	6715	65
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.008	mg	2336	23
Leadframe	Copper & its alloys	199.680	mg	supplier	alloy	Copper(CU)	7440-50-8		199.326	mg	998227	561482
				supplier	alloy	Tin(Sn)	7440-31-5		0.239	mg	1197	673
				supplier	alloy	Nickel	7440-02-0		0.115	mg	576	324
Soft solder	Solder	2.003	mg	supplier	solder	Tin(Sn)	7440-31-5		0.040	mg	19970	113
				supplier	solder	Silver(Ag)	7440-22-4		0.050	mg	24963	141
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.913	mg	955067	5387
				supplier	wire	Aluminium(Al)	84195-93-7		0.969	mg	1000000	2730
Encapsulation	Other Organic Materials	145.860	mg	supplier	mold compound	Silica Fused	60676-86-0		107.031	mg	733793	301496
				supplier	mold compound	Silica amorphous	7631-86-9		14.652	mg	100452	41273
				supplier	mold compound	Epoxy resin	25068-38-6		14.652	mg	100452	41273
				supplier	mold compound	Phenolic resin	29690-82-2		8.791	mg	60270	24763
				supplier	mold compound	Carbon Black	1333-86-4		0.734	mg	5033	2068
Finishing	Solder	3.063	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		3.063	mg	1000000	8628